

Material Content Data Sheet

RoHS

Sales Product Name	SPU03N60S5	**Issued**	11. December 2019
MA#	MA000798724		
Package	PG-TO251-3-341	**Weight***	381.66 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.326	0.61	0.61	6093	6093
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		195	
	non noble metal	iron	7439-89-6	0.248	0.07		651	
	non noble metal	copper	7440-50-8	248.124	65.01	65.10	650112	650958
wire	non noble metal	aluminium	7429-90-5	0.455	0.12	0.12	1192	1192
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.734	0.45		4542	
	plastics	brominated resin	-	1.857	0.49		4866	
	organic material	carbon black	1333-86-4	1.981	0.52		5191	
	plastics	epoxy resin	-	16.716	4.38		43798	
	inorganic material	silicondioxide	60676-86-0	101.534	26.60	32.44	266031	324428
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9799	9799
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1333	1333
solder	non noble metal	tin	7440-31-5	0.047	0.01		124	
	noble metal	silver	7440-22-4	0.059	0.02		155	
	non noble metal	lead	7439-92-1	2.259	0.59	0.62	5918	6197
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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